

SMD Auto COG Flex, Ceramic, 330 pF, 1%, 50 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, Automotive Grade, 0603



**Dimensions**

Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
T	0.8mm +/-0.15mm
S	0.58mm MIN
B	0.45mm +/-0.15mm

**Packaging Specifications**

<b>Packaging:</b>	T&R, 180mm, Paper Tape
<b>Packaging Quantity:</b>	4000

**General Information**

<b>Series:</b>	SMD Auto COG Flex
<b>Style:</b>	SMD Chip
<b>Description:</b>	SMD, MLCC, FT-CAP, Ultra-Stable, Automotive Grade
<b>Features:</b>	FT-CAP, Ultra-Stable, Automotive Grade
<b>RoHS:</b>	Yes
<b>Termination:</b>	Flexible Termination
<b>Marking:</b>	No
<b>Qualifications:</b>	AEC-Q200
<b>AEC-Q200:</b>	Yes
<b>Component Weight:</b>	4600 ug
<b>Shelf Life:</b>	78 Weeks
<b>MSL:</b>	1

**Specifications**

<b>Capacitance:</b>	330 pF
<b>Measurement Condition:</b>	1 MHz 1.0Vrms
<b>Capacitance Tolerance:</b>	1%
<b>Voltage DC:</b>	50 VDC
<b>Dielectric Withstanding Voltage:</b>	125 VDC
<b>Temperature Range:</b>	-55/+125°C
<b>Temperature Coefficient:</b>	COG
<b>Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC):</b>	30 ppm/C, 1MegaHz 1.0Vrms
<b>Dissipation Factor:</b>	0.1% 1 MHz 1.0Vrms
<b>Aging Rate:</b>	0% Loss/Decade Hour
<b>Insulation Resistance:</b>	100 GOhms